

Bill of Materials

TI DESIGNS

TIDA-00115

Item	Qty	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	10uF	CAP CER 10UF 16V 20% X5R 0805	TDK Corporation	C2012X5R1C106M/0.85	C1
2	3	.1uF	CAP CER 0.1UF 16V 10% X7R 0402	Murata Electronics North America	GRM155R71C104KA88D	C2, C4, C6
3	1	1uF	CAP CER 1UF 6.3V 10% X5R 0402	Yageo	CC0402KRX5R5BB105	C3
4	1	1uF	CAP CER 1UF 16V 20% X5R 0402	TDK Corporation	C1005X5R1C105M	C5
5	1	LED GREEN	LED 1.6X0.8MM 570NM GRN CLR SMD	Kingbright Corporation	APT1608CGCK	D1
6	4	2-Pin Header	CONN HEADER VERT SGL 2POS GOLD	3M	961102-6404-AR	J1, J4, JP1, JP2
7	1	Micro USB AB	CONN RCPT MICRO USB TYPE AB	TE Connectivity	1981584-1	J2
8	1	4-Pin Socket	SOCKET .050" GRID SIP 4 POS R/A	Mill-Max Manufacturing Corp	851-43-004-20-001000	J3
9	1	1K	RES 1.0K OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ102X	R1
10	1	10K	POT 10K OHM THUMBWHEEL CERM ST	Bourns Inc.	3352T-1-103LF	R2
11	3	0	RES 0.0 OHM 1/16W 0402 SMD	Yageo	RC0402JR-070RL	R3, R4, R5
12	1	47K	RES 47K OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ473X	R6
13	1	330	RES 330 OHM 1/10W 5% 0402 SMD	Panasonic - ECG	ERJ-2GEJ331X	R7
14	1	3.3V	IC LDO REG 3.3V 150MA SOT23-5	Texas Instruments	LP2985-33DBVR	REG1
15	2	Jumper	SHUNT JUMPER .1" BLACK GOLD	3M	969102-0000-DA	SHNT1, SHNT2
16	6	TP	PC TEST POINT MINIATURE SMT	Keystone Electronics	5019	TP1, TP2, TP3, TP4, TP5, TP6
17	1	MCU	Value Line Mixed Signal Microcontroller	Texas Instruments	MSP430G2131IRSA16R	U1
18	1	DRV8837DSG	LOW VOLTAGE H-BRIDGE IC	Texas Instruments	DRV8837DSG	U2
19	1	DC Motor	12V Brushed Motor	Anahiem Automation	BDD-38-63-12.0V-14200	

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